

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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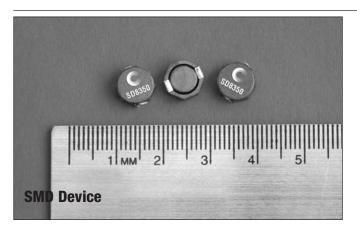






Shielded Power Inductors

SD8350 Series





- · Halogen free, lead free
- 125°C maximum total temperature operation
- Low-profile surface mount inductor
- 9.5 x 8.3 x 4.5mm shielded drum core
- Ferrite core material
- Inductance range from 1.5µH to 100µH
- Current range from 0.8 Amps to 9.1 Amps
- Frequency range up to 1MHz
- RoHS Compliant







Applications

- Server/notebook power
- High power LED driver, portable devices
- · Base station, telecom, and networking
- Battery chargers, RAM power supply
- Industrial and automotive power systems
- · Noise filtering output filter chokes
- Buck/boost converters, output converters

Environmental Data

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (ambient plus self temperature rise)
- Solder reflow temperature: J-STD-020D compliant

Packaging

• Supplied in tape and reel packaging, 750 parts per 13 inch dia. reel

| | Product Specifications | | | | | | |
|--------------|--------------------------|----------------|------------------------------|-----------------------------|--------------------------|--------------------------|-----------|
| Part Number | Rated Inductance (µH) | 0CL¹ μH±30% | I _{rms} ² (Amps) | l _{sat³} (Amps) | DCR mΩ @ 20°C Typical | DCR mΩ @ 20°C Maximum | K-factor⁴ |
| SD8350-1R8-R | 1.8 | 1.5 | 5.50 | 9.1 | 11.8 | 14.0 | 16.0 |
| SD8350-3R9-R | 3.9 | 3.2 | 4.50 | 6.3 | 16.2 | 19.0 | 9.6 |
| SD8350-4R7-R | 4.7 | 4.2 | 4.10 | 5.5 | 18.5 | 22.0 | 8.5 |
| SD8350-6R8-R | 6.8 | 6.8 | 3.90 | 4.4 | 20.8 | 25.0 | 7.6 |
| SD8350-100-R | 10 | 9.9 | 3.20 | 4.0 | 31.4 | 36.0 | 6.3 |
| SD8350-150-R | 15 | 13.6 | 2.30 | 2.9 | 45.0 | 53.0 | 5.3 |
| SD8350-220-R | 22 | 20.4 | 1.80 | 2.6 | 63.5 | 75.0 | 4.4 |
| SD8350-330-R | 33 | 31.4 | 1.40 | 2.2 | 111.4 | 125.0 | 3.5 |
| SD8350-470-R | 47 | 44.9 | 1.30 | 1.8 | 130.0 | 150.0 | 2.9 |
| SD8350-680-R | 68 | 65.1 | 1.00 | 1.5 | 200.8 | 240.0 | 2.4 |
| SD8350-101-R | 100 | 99.7 | 0.80 | 1.3 | 308.0 | 360.0 | 2.0 |

- 1. Open Circuit Inductance Test Parameters: 100kHz, 0.1V, 0.0Adc.
- 2. I_{rms}: DC current for an approximate \(\Delta \) To 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.
- 3. I_{sat} Amps peak for approximately 35% rolloff (@25°C)

- 4. K-factor: Used to determine B_{p-p} for core loss (see graph). $B_{p-p} = K^*L^*\Delta I, B_{p-p}$ (mT), K: (K factor from table), L: (Inductance in μH), ΔI (Peak to peak ripple current in Amps).
- Part Number Definition: SD8350-xxx-R
 SD8350 = Product code and size; -xxx = Inductance value in µH;
 R = decimal point; If no R is present, third character = # of zeros.
 R suffix = RoHS compliant

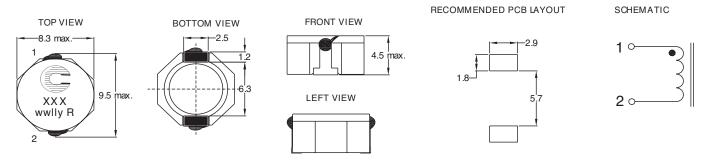
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Dimensions - mm

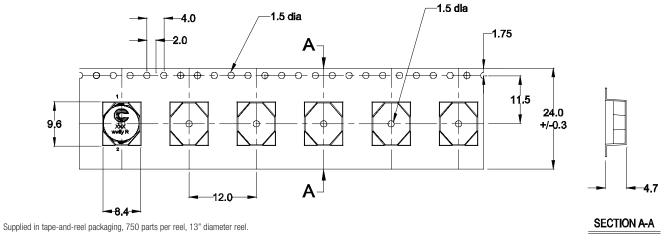


Part Marking: Coiltronics logo

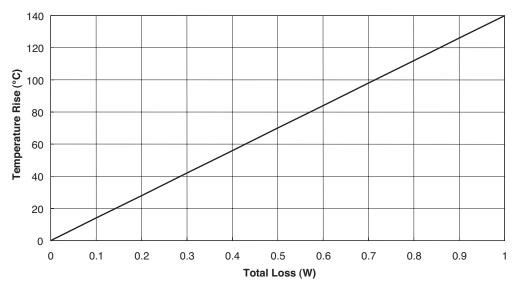
 $xxx = \text{Inductance value in } \mu \text{H. (R = Decimal point)}. \text{ If no R is present, third character} = \text{number of zeros} \qquad \text{wwlly - or - wwllyy} = \text{Date code}$

R = Revision level

Packaging Information - mm



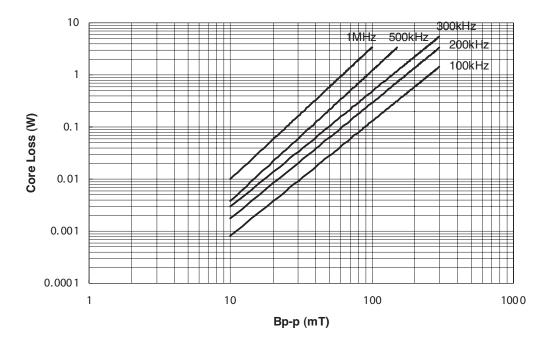
Temperature Rise vs. Total Loss



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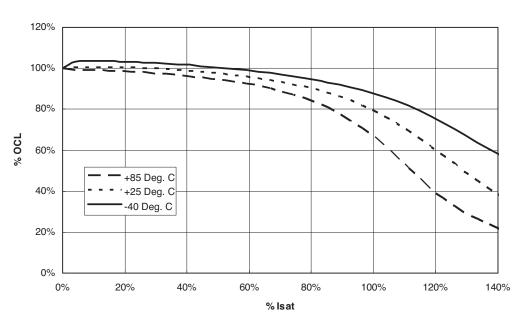


Core Loss



Inductance Characteristics





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Solder Reflow Profile

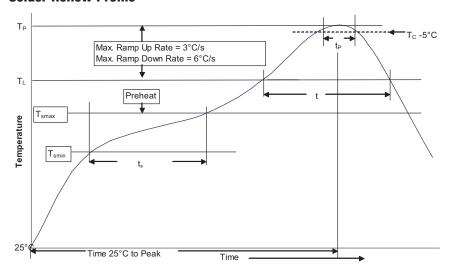


Table 1 - Standard SnPb Solder (T_C)

| Package | Volume mm ³ | Volume mm³ |
|-----------|---------------------------|---------------|
| Thickness | <350 | ≥350 |
| <2.5mm | 235°C | 220°C |
| ≥2.5mm | 220°C | 220°C |

Table 2 - Lead (Pb) Free Solder (Tc)

| Dookogo | Volume mm ³ | Volume mm³ | Volume mm ³ |
|-------------|---------------------------|---------------|---------------------------|
| Package | 1111111 | | |
| Thickness | <350 | 350 - 2000 | >2000 |
| <1.6mm | 260°C | 260°C | 260°C |
| 1.6 - 2.5mm | 260°C | 250°C | 245°C |
| >2.5mm | 250°C | 245°C | 245°C |

Reference JDEC J-STD-020D

| Profile Feature | | Lead (Pb) Free Solder | |
|---|---|---|--|
| • Temperature min. (T _{smin}) | 100°C | 150°C | |
| Temperature max. (T _{smax}) | 150°C | 200°C | |
| • Time (T _{smin} to T _{smax}) (t _s) | 60-120 Seconds | 60-120 Seconds | |
| Average ramp up rate T _{Smax} to T _p | | 3°C/ Second Max. | |
| Liquidous temperature (TL) | | 217°C | |
| Time at liquidous (t _L) | | 60-150 Seconds | |
| Peak package body temperature (Tp)* | | Table 2 | |
| Time $(t_p)^{**}$ within 5 °C of the specified classification temperature (T_c) | | 30 Seconds** | |
| Average ramp-down rate (T _p to T _{smax}) | | 6°C/ Second Max. | |
| Time 25°C to Peak Temperature | | 8 Minutes Max. | |
| | Temperature max. (T _{Smax}) Time (T _{Smin} to T _{Smax}) (t _S) Te T _{Smax} to T _p Tre (TL) Temperature (T _p)* C of the specified classification temperature (T _c) Trate (T _p to T _{Smax}) | • Temperature max. (T _{Smax}) • Time (T _{Smin} to T _{Smax}) (t _S) te T _{Smax} to T _p 3°C/ Second Max. Ire (TL) 183°C 60-150 Seconds temperature (T _P)* Table 1 °C of the specified classification temperature (T _C) 20 Seconds** rate (T _p to T _{Smax}) | |

 $^{^{\}star}$ Tolerance for peak profile temperature ($T_{\rm D}$) is defined as a supplier minimum and a user maximum.

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^{**} Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.